Amendments to the Claims:

This listing of claims will replace all prior versions, and listing, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended) A microwave circuit, comprising:

first and second microwave modules, each of which comprises a conductor sandwiched between upper and lower thickfilm dielectrics, and a ground shield surrounding the upper and lower thickfilm dielectrics in a direction transverse to the conductor; wherein, at a first end of each of the conductors, the conductor extends from beneath its upper thickfilm dielectric to terminate at a cut edge of its microwave module; the microwave modules being mounted with said cut edges facing one another;

a bridge conductor, electrically coupling the first ends of the conductors; and

a ground shield cap, oriented over the bridge conductor and electrically coupled to the ground shield ~~shields~~ surrounding the upper and lower thickfilm dielectrics of each of the microwave modules.

Claim 2 (Original) The microwave circuit of claim 1, wherein the bridge conductor comprises a ribbon bond.

Claim 3 (Original) The microwave circuit of claim 1, wherein the bridge conductor comprises a mesh bond.

Claim 4 (Original) The microwave circuit of claim 1, wherein the bridge conductor comprises a plurality of wire bonds.

Claim 5 (Currently Amended) The microwave circuit of claim 1, wherein the ground shield cap is electrically coupled to the ~~second~~ ground shield of each of the microwave modules ~~shields~~ via solder.

Claim 6 (Currently Amended) The microwave circuit of claim 1, wherein the ground shield cap is electrically coupled to the ~~second~~ ground shield of each of the microwave modules ~~shields~~ via conductive epoxy.

Claim 7 (Currently Amended) The microwave circuit of claim 1, wherein ~~the substrate of~~ each of the microwave ~~module~~ modules comprises a ceramic substrate.

Claim 8 (Currently Amended) The microwave circuit of claim 1, wherein the ~~first and second~~ upper and lower thickfilm dielectrics of each of the microwave modules ~~module~~ comprise a KQ dielectric.

Claim 9 (Currently Amended) A microwave circuit, comprising:

first and second microwave modules, each comprising i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from an end of the conductor terminating at or near a cut edge of the microwave module; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor; the microwave modules being mounted with said cut edges facing one another;

a bridge conductor, electrically coupling said ends of the conductors of the microwave modules; and

a ground shield cap, oriented over the bridge conductor and electrically coupled to the second ground shield of each ~~shields~~ of the microwave modules.

Claim 10 (Currently Amended) A method for coupling first and second microwave modules, wherein each microwave module comprises i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; and wherein, for each microwave module, at least the second dielectric and second

ground shield are recessed from a first end of the conductor; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor; the method comprising:

for each of the microwave modules, cutting the microwave module in proximity to the first end of the conductor, thereby defining a first edge of the microwave module;

mounting the microwave modules adjacent one another, with their first edges facing each other;

electrically coupling said first ends of the conductors of the microwave modules; and

placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each ~~shields~~ of the microwave modules.

Claim 11 (Currently Amended) The method of claim 10 wherein electrically coupling said first ends of the conductors of the microwave modules comprises placement of ~~the conductors are electrically coupled using~~ a ribbon bond.

Claim 12 (Currently Amended) The method of claim 10, wherein electrically coupling said first ends of the conductors of the microwave modules comprises placement of ~~the conductors are electrically coupled using~~ a mesh bond.

Claim 13 (Currently Amended) The method of claim 10, wherein electrically coupling said first ends of the conductors of the microwave modules comprises placement of ~~the conductors are electrically coupled using~~ a plurality of wire bonds.

Claim 14 (Currently Amended) The method of claim 10, wherein ~~the ground shield cap is~~ electrically coupling the ground shield cap ~~coupled~~ to the second ground shield of each of the microwave modules comprises placement of ~~shields via~~ solder.

Claim 15 (Currently Amended) The method of claim 10, wherein ~~the ground shield cap is~~ electrically coupling the ground shield cap ~~coupled~~ to the second ground

shield of each of the microwave modules comprises placement of ~~shields via~~ conductive epoxy.

Claim 16 (Currently Amended) A method, comprising:

selecting first and second microwave modules, each comprising i) a substrate, ii) a first ground shield formed on the substrate, iii) a first dielectric formed on the first ground shield, iv) a conductor formed on the first dielectric, v) a second dielectric formed on the conductor, and vi) a second ground shield formed on the second dielectric; wherein, for each microwave module, at least the second dielectric and second ground shield are recessed from an end of the conductor terminating at or near a cut edge of the microwave module; wherein, for each microwave module, the first ground shield and the second ground shield contact one another to surround the first dielectric and the second dielectric in a direction transverse to the conductor;

mounting the microwave modules adjacent one another, with said cut edge of the first microwave module facing said cut edge of the second microwave module;

electrically coupling said ends of the conductors of the microwave modules; and

placing a ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground ~~shields~~ shield of each of the microwave modules.

Claim 17 (Currently Amended) The method of claim 16, wherein ~~the conductors are~~ electrically coupling the ends of the conductors of the microwave modules comprises placement of ~~coupled using~~ a ribbon bond.

Claim 18 (Currently Amended) The method of claim 16, wherein ~~the conductors are~~ electrically coupling the ends of the conductors of the microwave modules comprises placement of ~~coupled using~~ a mesh bond.

Claim 19 (Currently Amended) The method of claim 16, wherein ~~the conductors are~~ electrically coupling the ends of the conductors of the microwave modules comprises placement of ~~coupled using~~ a plurality of wire bonds.

Claim 20 (Currently Amended) The method of claim 16, wherein ~~the ground shield cap is~~ electrically coupling the ground shield cap ~~coupled~~ to the second ground shield of each of the microwave modules comprises placement of ~~shields via~~ solder.

Claim 21 (Currently Amended) The method of claim 16, wherein ~~the ground shield cap is~~ electrically coupling the ground shield cap ~~coupled~~ to the second ground shield of each of the microwave modules comprises placement of ~~shields via~~ conductive epoxy.

Claim 22 (New) The microwave circuit of claim 1, wherein the ground shield cap has a top portion and at least one side portion extending away from the top portion, and wherein the ground shield cap forms a void between the top portion thereof, the at least one side portion thereof and the first and second microwave modules when the ground shield cap is electrically coupled to the ground shield surrounding the upper and lower thickfilm dielectrics of each of the microwave modules.

Claim 23 (New) The microwave circuit of claim 9, wherein the ground shield cap has a top portion and at least one side portion extending away from the top portion, and wherein the ground shield cap forms a void between the top portion thereof, the at least one side portion thereof and the first and second microwave modules when the ground shield cap is electrically coupled to the second ground shield of each of the microwave modules.

Claim 24 (New) The method of claim 10, wherein placing the ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules further comprises forming a void between a top portion of the ground shield cap, at least one side portion of the ground shield cap and the first and second modules.

Claim 25 (New) The method of claim 16, wherein placing the ground shield cap over the conductor coupling, and electrically coupling the ground shield cap to the second ground shield of each of the microwave modules further comprises forming a void

between a top portion of the ground shield cap, at least one side portion of the ground shield cap and the first and second modules.